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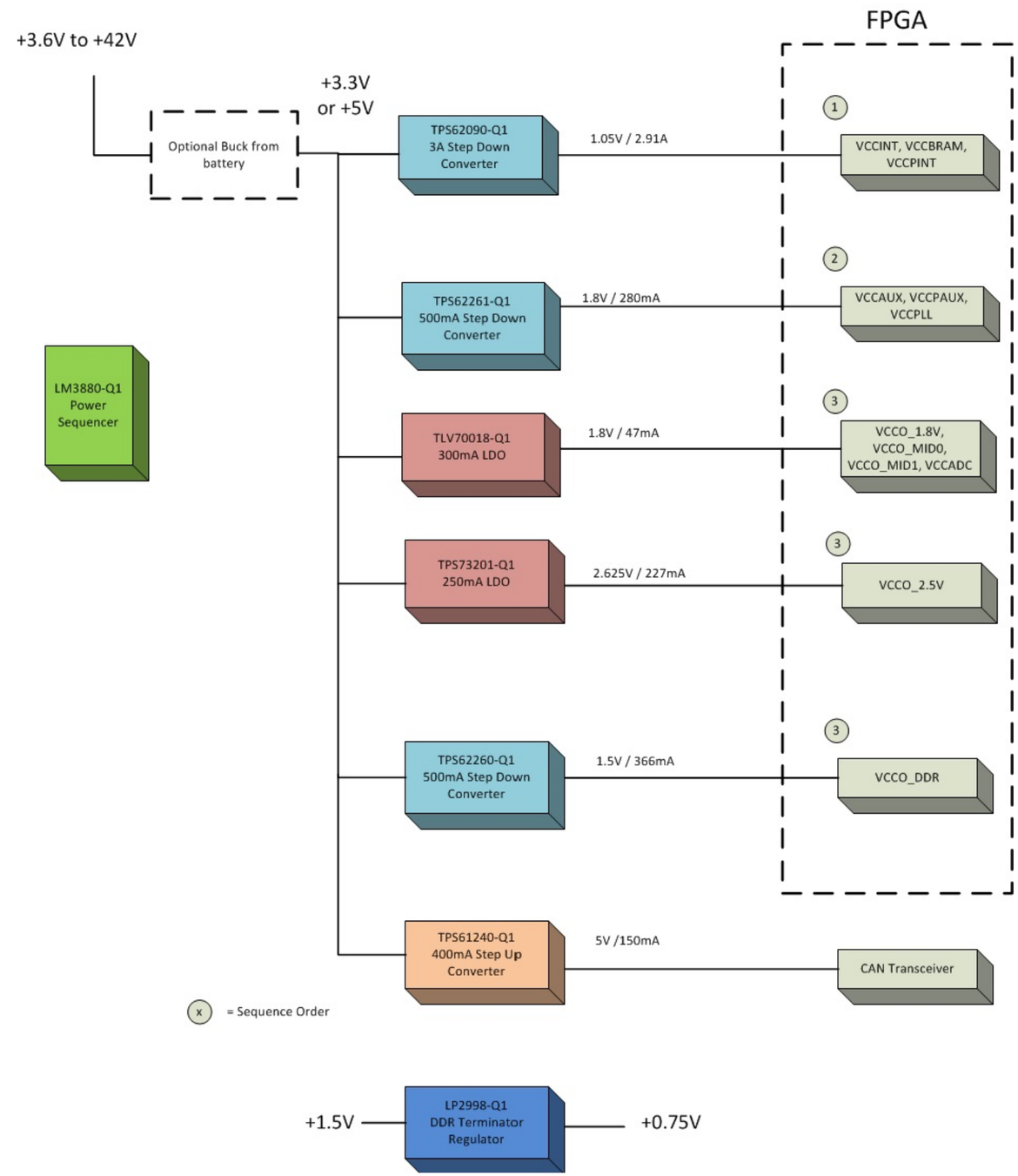
Xilinx Zynq 7020 Power Reference Design for Automotive ADAS



Designed for: Public Release		Mod. Date: 12/2/2014	
Project Title: TIDA-00390			
Number: TIDA-00390	Rev: E1	Sheet Title:	
SVN Rev: Version control disabled		Assembly Variant: 001	Sheet: 1 of 7
Drawn By:		File: Cover Sheet_ANSI-B.SchDoc	Size: B
Engineer: Sami Sirhan		Contact: http://www.ti.com/support	

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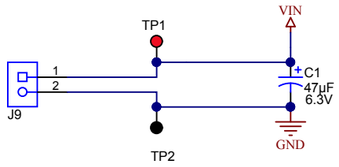
Input Terminals and Sequencer

VIN: 3.3V or 5V



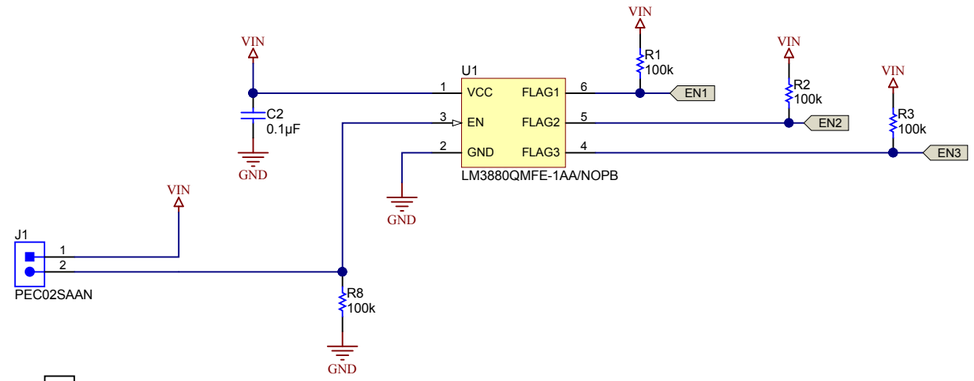
For 3.3V Operation:

SH-J8 = Open

For 5V Operation:

SH-J8 = Installed

Sequencer



SH-J1 Options:

Installed - Sequencer Enabled

Open - Sequencer Disabled

Number: TIDA-00390	Rev: E1	Designed for: Public Release	Mod. Date: 12/2/2014
SVN Rev: Version control disabled		Project Title: TIDA-00390	
Drawn By:		Sheet Title:	
Engineer: Sami Sirhan		Assembly Variant: 001	Sheet: 2 of 7
		File: Sequencer.SchDoc	Size: B
		Contact: http://www.ti.com/support	

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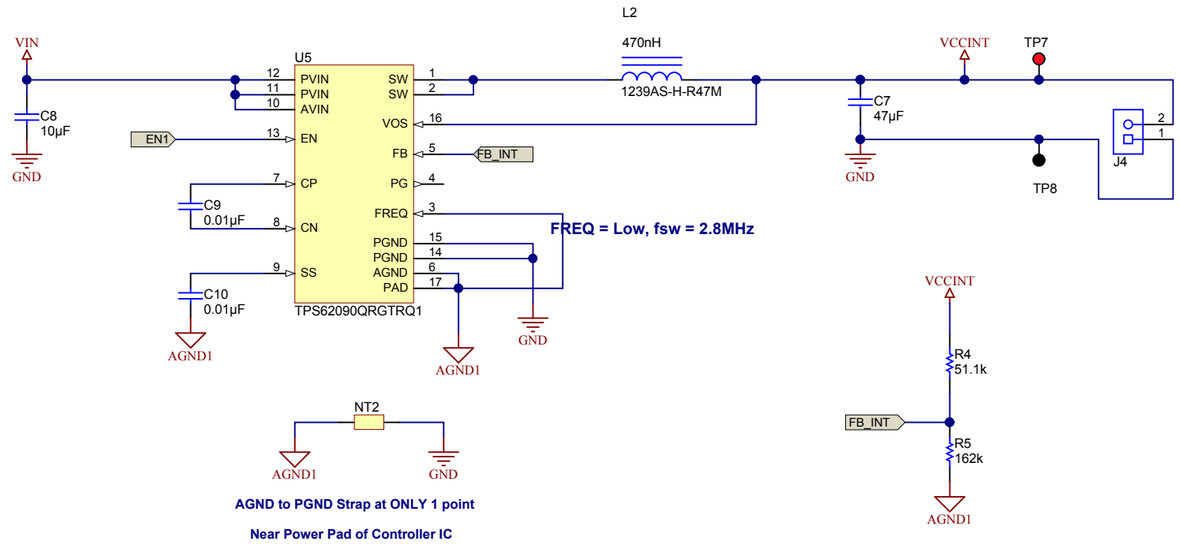
VCCINT: 1.05V / 1.87A



Orderable: EVM_orderable	Designed for: Public Release	Mod. Date: 12/2/2014
TID #: TID	Project Title: TIDA-00390	
Number: TIDA-00390 Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 7
Drawn By:	File: VCCINT.SchDoc	Size: B
Engineer: Sami Sirhan	Contact: http://www.ti.com/support	

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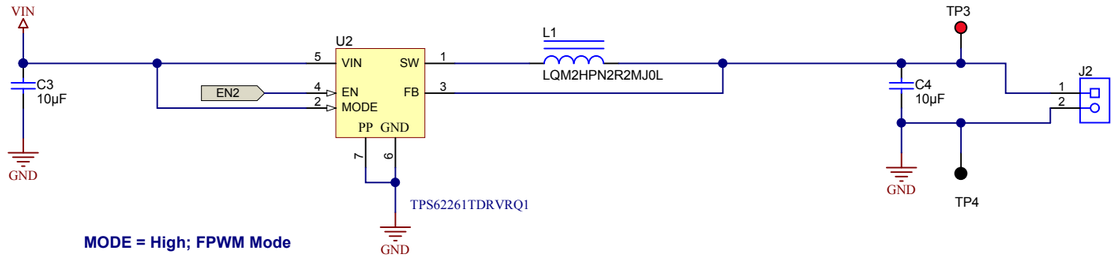
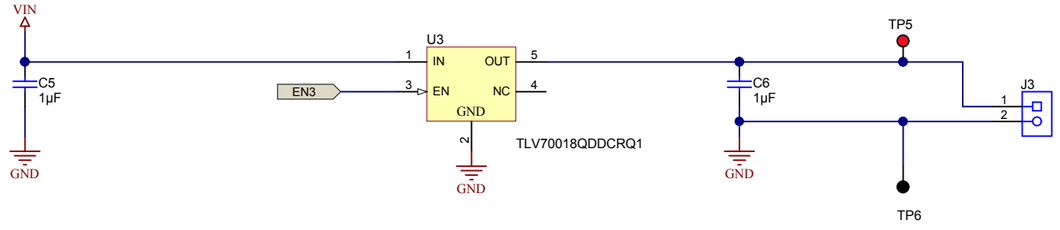
VCCAUX: 1.8V / 280mA



MODE = High; FPWM Mode

VCCO1.8V: 1.8V / 47mA



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Number: TIDA-00390 Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 4 of 7
Drawn By:	File: VCCAUX_VCCO1.8V.SchDoc	Size: B
Engineer: Sami Sirhan	Contact: http://www.ti.com/support	

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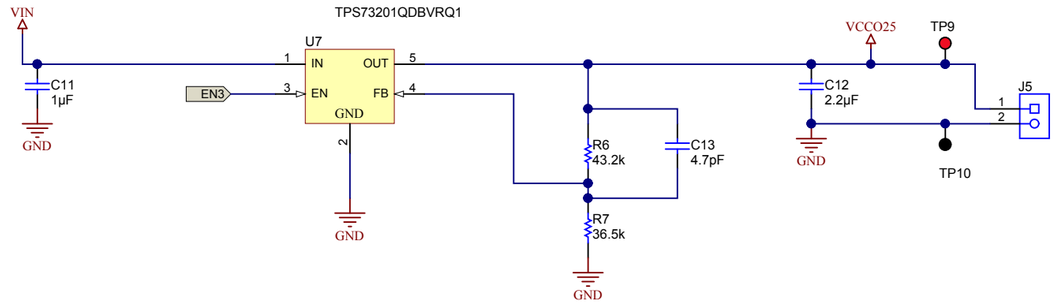
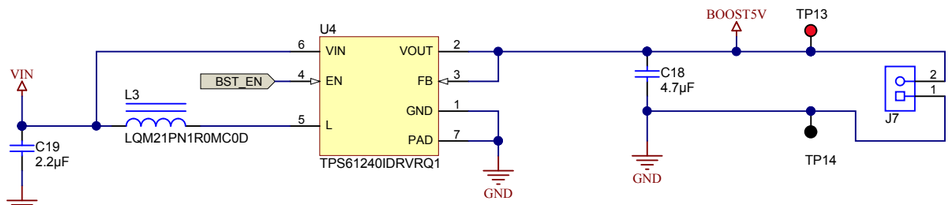
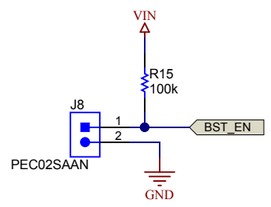
VCCO_2.5V: 2.625V / 227mA



BOOST5V: 5V / 150mA





SH-J8 Options:

Installed - BOOST5V Disabled

Open - BOOST5V Enabled

SH-J8

Orderable: EVM_orderable	Designed for: Public Release	Mod. Date: 12/2/2014
TID #: TID	Project Title: TIDA-00390	
Number: TIDA-00390 Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 5 of 7
Drawn By:	File: VCCO25_BOOST5V.SchDoc	Size: B
Engineer: Sami Sirhan	Contact: http://www.ti.com/support	

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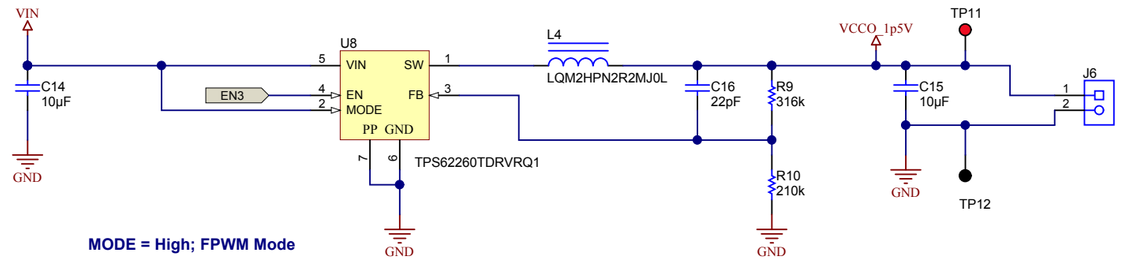
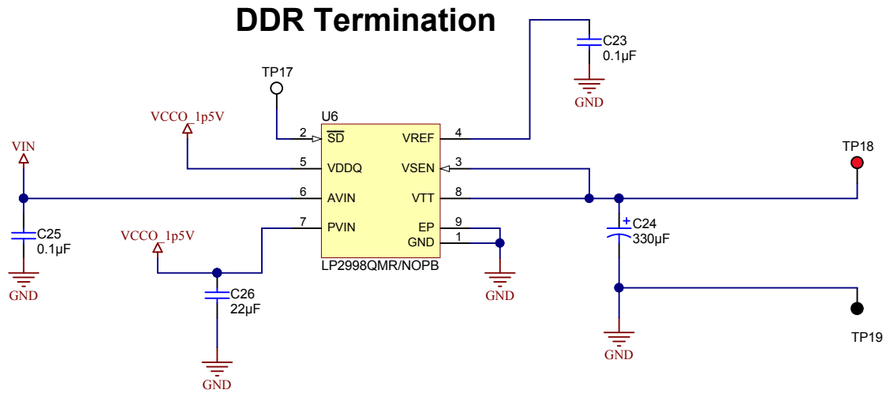
VCCO_DDR: 1.5V / 366mA



DDR Termination



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TID #: TID	Project Title: TIDA-00390	
Number: TIDA-00390 Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 6 of 7
Drawn By:	File: VCCO_DDR.SchDoc	Size: B
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DNP FID1

DNP FID2

DNP FID3

FID4

FID5

FID6

PCB Number: TIDA-00390
PCB Rev: E1

PCB
LOGO
Texas Instruments

PCB
LOGO
Pb-Free Symbol

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Designed for: Public Release		Mod. Date: 12/2/2014	
Project Title: TIDA-00390			
Number: TIDA-00390	Rev: E1	Sheet Title:	
SVN Rev: Version control disabled		Assembly Variant: 001	Sheet: 7 of 7
Drawn By:		File: Hardware_ANSI-B.SchDoc	Size: B
Engineer: Sami Sirhan		Contact: http://www.ti.com/support	

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